IEEE Symposium on Low-Power and High-Speed Chips

COOL Chips XIV

CALL FOR PARTICIPATION

COOL Chips is an International Symposium initiated in 1998 to present advancement of low-power and high-speed chips. The symposium covers leading-edge technologies in all areas of microprocessors and their applications.
The COOL Chips XIV is to be held in Yokohama on April 20-22, 2011, and is targeted at the architecture, design and implementation of chips with special emphasis on the areas listed below.

- **Low Power-High Performance Processors for Multimedia, Digital Consumer Electronics, Mobile, Graphics, Encryption, Robotics, Automotive, Networking, Medical, Healthcare, and Biometrics.**
- **Novel Architectures and Schemes for Single Core, Multi-Core, Embedded Systems, Reconfigurable Computing, Grid, Ubiquitous, Dependable Computing, GALS and Wireless.**
- **Cool Software including - Parallel Schedulers, Embedded Real-time Operating System, Binary Translations, Compiler Issues and Low Power Techniques.**

Dates and Location

April 20-22, 2011

Yokohama Joho Bunka Center, Yokohama, Japan
(Yokohama Media & Communications Center, Yokohama, Japan)

Keynote Presentations

- "The Truths and Myths of Embedded Computing", **Shekhar Borkar** *(Intel, USA)*
- "AMD's Zacate, Low Power Fusion APU", **Denis Foley** *(Advanced Micro Devices, USA)*
- "Worldwide RMC Mobile Platform Solution", **Juha M. Heikkilä** *(Renesas Mobile Corp., Finland)*
- "From Multi-Core CPU to Many-Core GPU", **Toru Baji** *(NVIDIA Japan, Japan)*
- " Entering the Era of Crossover SoCs", **Patrick Lysaght** *(Xilinx, USA)*

Invited Presentations

- "The Correspondence between Architecture and Application for High Speed Vision Chips", **Masatoshi Ishikawa** *(Tokyo Univ., Japan)*
- "Toward Machine Vision Technology Overcoming the Pixel Resolution Limit, -- From 3D vision to medical imaging --", **Takafumi Aoki** *(Tohoku Univ., Japan)*
- "Full Software Implementation of Real-time ISDB-T Modulator on Dynamically Reconfigurable SoC Using Practical Co-design Environment", **Toru Awashima** *(Renesas Electronics Corp., Japan)*

Panel Discussion

- Topics: Impact on society by fusion and harmony of mobile devices, servers, and networks
  -- Their direction of evolutions and optimal roles --
  Organizer/Modelator: **Masato Motomura** *(NEC, Japan)*

Special Sessions (invited lectures)

- "Trusted MpSoC Platforms for Safety Related Applications", **Rolf Ernst** *(Technische Universitat Braunschweig, Germany)*
- "Power Measurement, Characterization and Estimation of Microprocessor-Based Systems", **Naehyuck Chang** *(Seoul National University, Korea)*

For more information, please visit <**http://www.coolchips.org/**>

Symposium Registration

In order to make a registration, please use COOL Chips XIV REGISTRATION FORM on web site at
< http://www.coolchips.org/ >

REGISTRATION FEES

Registration Fees include a copy of the proceedings (copies of speakers' slides) of all plenary and technical sessions and special sessions presented on April 20-22, 2011.

	Early Registration by **April 6**, '11	Late Registration from April 7, '11
Member of any of IEEE IEICE, IPSJ or ACM	40,000 yen	50,000 yen
Non-Member	50,000 yen	63,000 yen
Student (Member)	13,000 yen	16,000 yen
Student (Non-Member)	17,000 yen	20,000 yen

PAYMENT

For attendees excluding presenters:
- On-site cash payment is strongly recommended.
- Credit cards (VISA/MasterCard) are necessarily acceptable.

For presenters of accepted papers:
- Credit cards (VISA/MasterCard) are only acceptable.

Detailed information is available on the web site.

Notes:
1. Credit card charges will be billed in Yen.
2. Personal checks, bank drafts, and traveler's checks are not acceptable.

Accommodations

HOTEL RESERVATIONS

A special group rate is available for COOL Chips XIV attendees for Hotel Monterey Yokohama and Hotel New Grand.

CONTACT to

COOL Chips XIV Organizing Committee Secretaries
E-mail:cool_XIV@coolchips.org   http://www.coolchips.org/

(As of April 4, 2011)